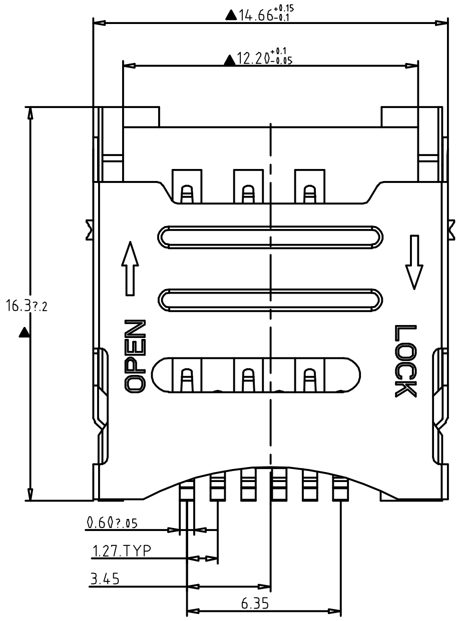
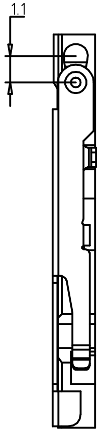
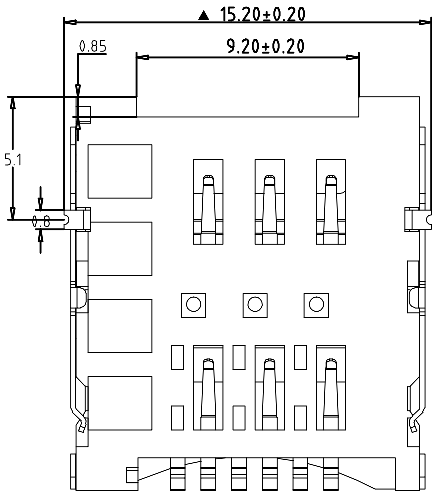
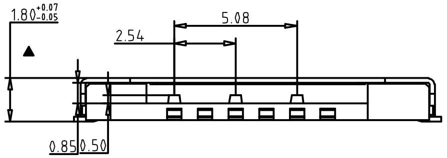
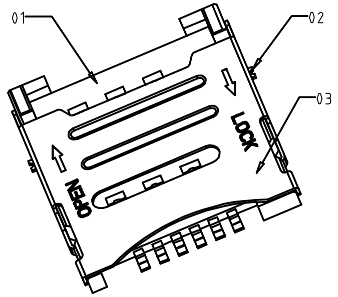
RoHS HSF

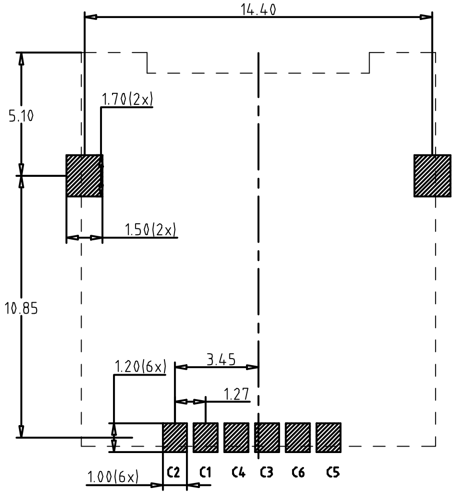




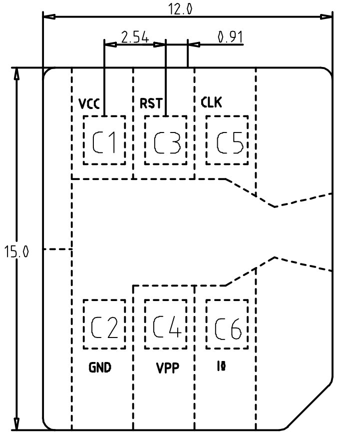








PCB LAYOUT



MICRO SIM

一、材质和镀涂:

1、胶芯: LCP, UL 94 V - 0,黑色

?、端子: 磷铜C5210-H, T=0.15, 镍底镀金

?、外壳: 不锈钢 SUS304 T=0.2

二、技术参数:

接触电阻: 100mΩ Max

绝缘阻抗: 1000MΩ Min(500DC)

额定电流: 每个接触件1A Max

额定电压: 30V Max(DC)

耐　　压: 500V r.m.s/min

使用温度: -40℃~85℃

湿　　度: 90%~95%

寿　　命: >3000次

PIN NO.	NAME	PIN NO.	NAME
C1	VCC	C4	VPP
C2	GND	C5	CLK
C3	RST	C6	I0

Bossie（博锡）

E	PRODUCT SPEC.	MICRO SIM	
TITLE:	翻盖式 MicroSIM卡 卡座		
PART NO.	BX-SIM-1.8HJ		
FILE NAME.			
SCALE	1:1	UNIT:mm	A4
SHEET:1 of 1			

工程变更通知单号 ECN(DCN) NO.	版次 REV	日期 DATE	说明 DESCRIPTION	改变 CHANGE	承认 APPRO.
	B		修改实物与图纸相符		
——————	A		NEW RELEASE		

General	Angle
X±0.50	X°±2°
.X±0.30	.X°±1°
.XX±0.20	.XX°±0.5°

GENERAL TOLERANCE UNLESS OTHERWISE NOTED

设计 DESIGN

校阅 CHECK

承认 APPRO.